

* Metal Semiconductor Junctions

Topics:

(10-15 Marks)

06/10/2014

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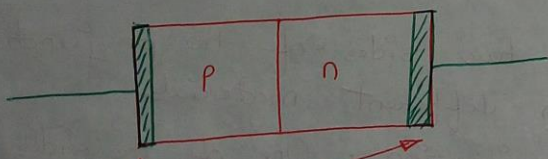
- Schottky barrier diode: Qualitative characteristics, Ideal junction properties, non-ideal effects on barrier height and I-V characteristics
- Metal Semiconductor ohmic contacts: Ideal non-rectifying barrier, Tunneling barrier, specific contact resistance.

)- Introduction

- P-N junctions are called "homojunctions" because the p and n regions of the junction are formed in the same semiconductor material.
- Apart of pn junctions, there are two interesting junctions.
 - a) Heterojunctions: The two sides of the pn junction may be formed in different materials
 - b) Metal-semiconductor junction: One of the sides of a junction may be a metal and other side of a junction can be a semiconductor made.
- These devices are important and need to be understood well to fully exploit their potential.

- Metal-semiconductor junctions can be either rectifying or ohmic in nature. 02
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- In order to understand whether a metal-semiconductor contact is rectifying or non-rectifying (ohmic), we have to investigate \rightarrow the mechanism of barrier formation at the Metal-semiconductor interface.
- Ohmic contacts play a vital role in deciding the characteristics of semiconductor devices.
- The rectifying metal-semiconductor junctions are called "Schottky barrier Diode".

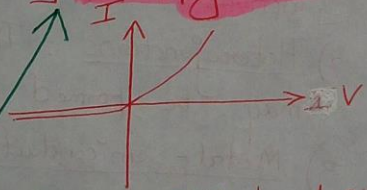
[Majority carrier device] \Rightarrow Symbol



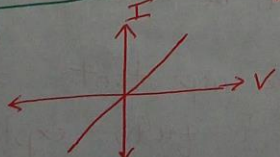
Metal-semiconductor contacts

1] Rectifying Contact

• They have I-V characteristics as pn junction.



2] Ohmic Contacts

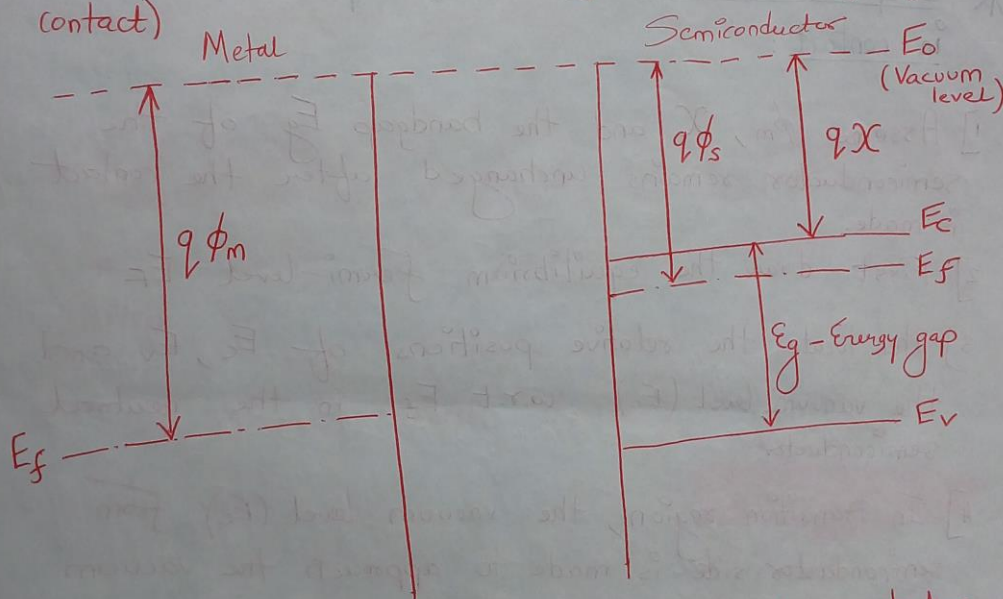


In a good ohmic contact, its resistance should be v. small i.e. large current should flow in both forward and reverse directions with very small voltage drop

* Important Terms in Metal-Semiconductor junction ⁰³

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• Let's look at the energy band diagram of a metal-n-type semiconductor contact with $\phi_m > \phi_s$ when two materials isolated from each other (Before contact)



• **Vacuum level**: It represents the energy of an electron at rest outside the material. Vacuum level is taken as reference level with which all other energy levels are measured.

• **Work function** of a material is the energy required to bring an electron from Fermi-level to vacuum level.

ϕ_m - Metal work function ; ϕ_s - Semiconductor work function

• **Electron affinity (χ)** of the semiconductor is the energy difference between conduction band (E_c) and vacuum level (E_0).

* Steps to draw the EBD of any two materials in contact:

1] Assume ϕ_m , χ and the bandgap E_g of the semiconductor remains unchanged after the contact is made.

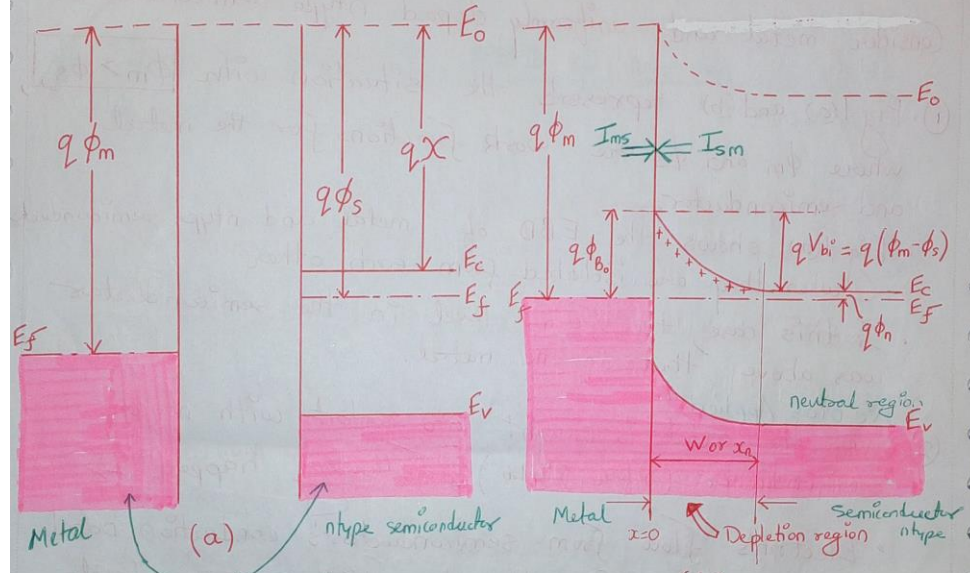
2] First draw the equilibrium Fermi-level E_F

3] Then locate the relative positions of E_c , E_v and the vacuum level (E_0) w.r.t E_F in the neutral semiconductor.

4] In transition region, the vacuum level (E_0) from semiconductor side is made to approach the vacuum level (E_0) on the metal side gradually to preserve its continuity.

5] The band edges E_c and E_v follow the same variations as the vacuum level (E_0), because χ remains unchanged.

→ The Schottky barrier diode - Metal Semiconductors ⁰⁵
contact/junction : (Rectifying contact)



the shaded portion means that all states are filled

fig 1: EBD of a metal - ntype semiconductor for $\phi_m > \phi_s$
 a) Before contact (Two materials are isolated from each other)
 b) Thermal equilibrium situation after the contact is made

* Formation of Schottky Barrier :

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- Qualitative Analysis :

Consider metal and uniformly doped n-type semiconductors

①. Fig 1(a) and (b) represents the situation with $\phi_m > \phi_s$, where ϕ_m and ϕ_s are work functions for the metal and semiconductor.

• Fig 1(a) shows the EBD of metal and n-type semiconductor when they are isolated from each other

• In this case, the Fermi level in the semiconductor was above that in the metal.

"No bias Applied"

② When the metal is brought into contact with n-type semiconductor (refer Fig 1.b), following happens \Rightarrow

• Electron's flow from semiconductor's conduction band into the metal (as they have higher energy levels than electrons in the metal), by the process of "thermionic emission".

• This process continues till Fermi levels in metal and n-type semiconductor are aligned.

This results in upward bending of energy bands in the semiconductor (Fig 1.b)

• Electrons that flow into the metal leave behind a positively charged ionized donor's, creating a depletion layer of thickness 'W' in the semiconductor.

• It is evident from fig 1.b that the band-bending in the semiconductor is equal to the difference metal and semiconductor work function.

• On the semiconductor side, V_{bi} is built-in potential barrier. i.e. $V_{bi} = \phi_m - \phi_s$

$V_{bi} \rightarrow$ Potential barrier ($\phi_m - \phi_s$) the electrons in the C.B of n-type semiconductor face in trying to reach the metal side.

• Also, $V_{bi} = \phi_{B0} - \phi_n$

• Parameter " ϕ_{B0} " is the ideal barrier height (viewed from metal towards semiconductor)

• ϕ_{B0} - Potential barrier seen by electrons in the metal trying to move into the semiconductor.

\rightarrow It is also known as "Schottky Barrier".

$$\phi_{B0} = \phi_m - \chi$$

where χ is electron affinity in the semiconductor

Extra!

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• In thermal equilibrium case (refer fig 1.b)

At a temperature $T \Rightarrow$

- A small fraction of CB e^- s will have sufficient energy to cross the barrier.
- These e^- s flow into the metal and cause a current I_{ms} , which flows from Metal to semiconductor.
- This current is exactly balanced by an equal and opposite current I_{sm} caused by the electron flow from the metal into semiconductor.

③ Forward Bias (Semiconductor -ve w.r.t Metal):

- When the semiconductor is biased negative w.r.t the metal by a voltage V_a , the barrier for electrons in the n-type Semiconductor decreases from qV_{bi} to $q(V_{bi} - V_a)$.

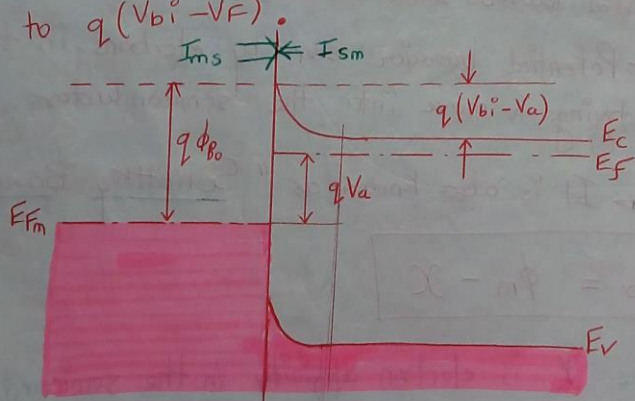


fig (1.c): Ideal EBD of a Metal-n-type semiconductor under forward bias for $\phi_m > \phi_s$

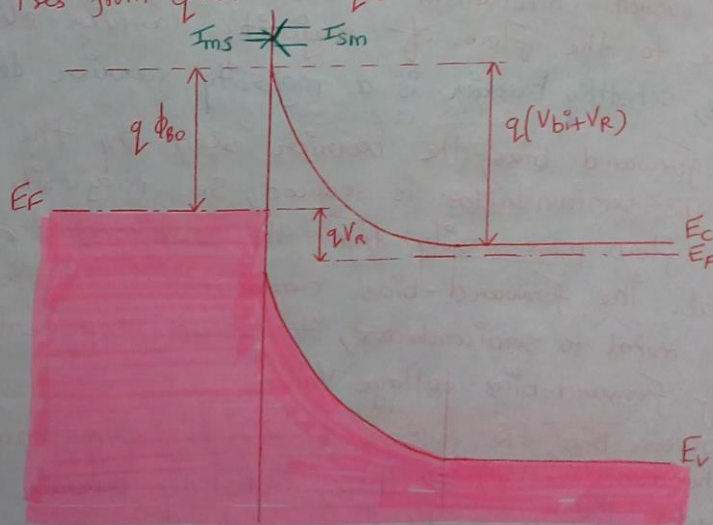
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- That is, more electrons can now flow from the n-type semiconductor to the metal and I_{ms} rises above its equilibrium value.
- In this case, the barrier $\phi_{B0} = \phi_m - \chi$ remains relatively unaffected by the applied voltage. Thus, I_{sm} remains unchanged from equilibrium case because there is no voltage drop across the metal and $q\phi_{B0}$ remains almost unaltered.
- Therefore, there is a net current flow from metal to semiconductor.

④ Reverse bias (Semiconductor is +ve w.r.t Metal):

- When semiconductor is biased positive w.r.t metal by a voltage V_R , the semiconductor-to-metal barrier height rises from qV_{bi} to $q(V_{bi} + V_R)$.

fig (1.d)
EBD of a metal-n-type semiconductor under reverse bias for the case $\phi_m > \phi_s$



- Thus, e^- s in the semiconductor see a larger barrier to cross and reach to metal. i.e. I_{ms} reduces below the equilibrium value, while the barrier height ϕ_{B0} remains constant i.e. I_{sm} is constant (almost unaffected). Thus
- Thus, a small reverse current flows.

Justify why a metal-n-type semiconductor is a rectifying contact (Schottky barrier diode): For $(\phi_m > \phi_s)$

- The EBDs versus bias voltage for the metal-semiconductor junction shown in fig (1.c) and (1.d) are similar to those of pn junction.
- Because of the similarity, we expect the I-V characteristics of Schottky barrier junction to be similar to the exponential behavior of pn junction.
- The current mechanism in such case, however, is due to the flow of majority carrier electrons. (Hence, Schottky barrier is a majority carrier device)
- In forward bias, the barrier seen by the electrons in the semiconductor is reduced, so majority carrier e^- s flow more easily from the semiconductor into the metal. The forward-bias current is in the direction from metal to semiconductor, it is an exponential function of forward-bias voltage V_a .
- In reverse bias, the reverse current is very small & saturates. (ideally) \Rightarrow Thus, Schottky barrier junction acts like a rectifying contact.